Title:	*Sample Preparation for Back Side Circuit Modification (FIB Circuit Edit)*
Training duration:	*3 days*
Training cost:	*Groups of 1 – 3 trainees, US$3600 per group*
Background required:	*Basic operator training for Chip-Unzip, or similar backside sample preparation system*
Student Objective:	*Ability to independently perform decapsulation, silicon thinning, polishing, and cleaning of Flip-Chip packaged integrated circuits for backside circuit edit.*
Equipment:	*Chip-Unzip, ASAP, high-speed CNC milling machine*
Syllabus:	*Available at* www.partbeamsystech.com/training.html